AMENDMENTS TO THE SPECIFICATION:

Please amend the paragraph on page 3, beginning at line 3 as follows:

The substrate 16 of the semiconductor package 10 is provided with solder [[bolls]]balls 20 electrically connected to the semiconductor chip 12 through vias (not shown) for being electrically connected to a first external printed wiring board 24. A connector 22 is electrically connected to the substrate 16 by the process of the surface mount technology and electrically connected to the semiconductor chip 12 for electrically connecting the semiconductor chip 12 to an external electronic device, such as a second external printed wiring board (not shown). As shown in the figure, the solder balls 20 of the substrate 16 are electrically connected to the first external printed wiring board 24 by way of the bottom of the substrate 16, and the connector 22 is electrically connected to the second external printed wiring board by way of the top of the substrate 16. It will be apparent to those skilled in the art that the connector 22 can be mounted in various directions so that the semiconductor package 10 is electrically connected to the second external printed wiring board in the various directions.

Please amend the paragraph on page 3, beginning at line 23 as follows:

The substrate 36 of the semiconductor package 30 is provided with solder [[bolls]]balls 40 electrically connected to the semiconductor chip 32 through vias (not shown) for being electrically connected to a first external printed wiring board (not shown). A connector 42 is electrically connected to the periphery of the substrate 36 by the process of the surface mount technology and electrically connected to the semiconductor chip 12 for being electrically connected the semiconductor chip 12 to a second external printed wiring board (not shown) or an external electronic device. As shown in the figure, the solder [[bolls]]balls 40 of the substrate 36 are electrically connected to the first external printed wiring board by way of the bottom of the substrate 36, and the connector 42 is electrically connected to the second external printed wiring board by way of the top of the substrate 36.